

Physical Vapor Deposition

Sputtering Targets, Evaporation Slugs and Metal Foils

Today, Physical Vapor Deposition (PVD) technique is used in a variety of applications, including fabrication of microelectronic devices, interconnects, flat panel displays, photovoltaics, battery and fuel cell electrodes, diffusion barriers, optical and conductive coatings, and surface modifications. PVD is a vacuum deposition process used to deposit thin layers of materials, in the range of few nanometers to several micrometers.

Selected Circular Sputtering Targets (purity, trace metals basis)

- Aluminum 99.9995% (Prod. No. 749036)
- Titanium 99.995% (Prod. No. 749044)
- Zinc oxide 99.99% (Prod. No. 752681)
- Indium tin oxide 99.99% (Prod. No. 752657)



Selected Evaporation Slugs (purity, trace metals basis)

- Iridium 99.9% (Prod. No. 449229)
- Titanium $\geq 99.99\%$ (Prod. No. 433675)
- Platinum 99.99% (Prod. No. 373230)
- Palladium 99.95% (Prod. No. 373206)



Selected Metal Foils (purity, trace metals basis)

- Aluminum 99.999% (Prod. No. 266957)
- Cadmium $\geq 99.99\%$ (Prod. No. 265411)
- Cobalt $\geq 99.99\%$ (Prod. No. 266671)
- Copper 99.999% (Prod. No. 266744)
- Gold 99.99% (Prod. No. 265829)



Custom designed materials, including metal filled crucibles for Molecular Beam Epitaxy (MBE), are also available through our **Hard Materials Center of Excellence**. To inquire, please contact hardmaterials@sial.com.

Aldrich Materials Science offers a variety of high purity materials for PVD techniques.

For complete list of materials and detailed product information, visit

aldrich.com/pvd